Heat has become the biggest bottleneck in computing. The latest processors promise higher performance, but only 50% or less is realized in actual devices. While processors continue to advance and generate more heat, thermal solutions have not kept pace. Thermal is the only aspect of modern day computing that still uses century old technology. In today’s devices, what often determines performance is the capability of the thermal solution, not the sophistication of the processor.

AirJet® Mini generates 1750 Pascals of back pressure, ensuring air flow into and out from product enclosures. When integrated into a compute platform with processor die temperature of 85°C, AirJet® Mini removes a net 4.25 Watts of heat at a silent 21 dBA noise level, while consuming 1 Watt of power.

For example, 11 mm thick fanless 13” notebooks have a thermal limit of only 10 Watts sustained processor power. In a similar 11 mm thick notebook, 4 x AirJet® Mini can support a sustained processor power of 20 Watts, at a silent 27 dBA noise level, increasing processor performance by 2x.

In today’s devices, what often determines performance is the capability of the thermal solution, not the sophistication of the processor. Thanks to AirJet® Mini, premium super slim notebooks can now deliver on the promise of cutting edge processor technology. Do more.